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(54) **WATER BLOCK WITH AIR-COOLING
MODULE AND MULTI-LAYER
HEAT-CONDUCTING STRUCTURE**

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(57) **ABSTRACT**

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A water block includes an air-cooling module, a multi-layer heat-conducting structure and a water pump. The air-cooling module is provided above the water pump, and a pump bottom casing is provided below the water pump. The multi-layer heat-conducting structure is provided below the pump bottom casing, and a heat-conducting bottom casing is provided below the multi-layer heat-conducting structure. The multi-layer heat-conducting structure is formed, from top to bottom, by a top layer, a main body, an interlayer, and a bottom layer. A multi-layer heat-dissipation fin is provided inside the multi-layer heat-conducting structure.

